

REMARKS

Claims 1, 12, 14 and 15, and 22-26 are pending in this application. Reconsideration and allowance are respectfully requested.

The Examiner states on page 2 of the Office action dated May 27, 2005, that claim 15 depended from non-elected claim 5 and was not examined. Applicants respectfully request that this statement be reconsidered and that claim 15 be examined, in view of the Amendment dated March 8, 2005, that specifically and unambiguously amended the dependency of claim 15 from claim 5 to depend from claim 1. In view of claim 15 as properly amended not being accorded an examination, Applicants also respectfully request the Examiner withdraw the finality of the instant Office action mailed May 27, 2005.

Acknowledgement of receipt of the priority document, which was filed in the parent application on which this application is based, now U.S. Patent No. 6,759,739 on May 19, 2003, is respectfully requested.

Claim 1 was rejected under 35 USC 112 for being indefinite, as the word "bump" did not have the word "a" there-before. Applicants have amended claims 1 and 15 to add the word "a" before "bump" as suggested by the Examiner. The Examiner also requested clarification regarding whether the words in claim 1 regarding the joining of the reinforcing sheet to the body on both faces or on just one face. The amendment of claim 1 is believed to make this rejection moot.

Claims 1, 14, and 15 stand rejected as being anticipated by Kamoi (JP application 11-74649). Applicants respectfully traverse. The Examiner states that Kamoi in Figures 1 to 2d show the device of claim 1, wherein the sheet 6a, 6b is the reinforcing sheet. The epoxy resin adhesive layer 6a, 6b set forth in Kamoi (JP 11-74649 a), which the Examiner has regarded as a reinforcing sheet, is bonding epoxy used to bond the surface wiring conductors 3a, 3b to the insulating substrate 1a, 1b. Paragraphs [0037] and [0038] of Kamoi read "A surficial wiring conductor 3a, 3b made of a metal foil is fixed to an insulating substrate 1a, 1b through an bonding layer 6a, 6b of cured epoxy resin. The bonding layer 6a, 6b of cured epoxy resin is made of a cured product of an epoxy resin such as an epoxy of bisphenol A type, ..., and serves to join the surficial wiring conductor 3a, 3b made of a metal foil to the insulating substrate 1a, 1b for the strong bonding therebetween, and to prevent moisture from intruding from between the insulating substrate 1a, 1b and the surficial wiring conductor 3a, 3b made of a metal foil". As

such, the epoxy resin layer 6a, 6b in Kamoi is not intended to function as a reinforcing sheet and in fact does not function as a reinforcing sheet.


Additionally, while the claims 22 et seq are not explicitly addressed with respect to Kamoi, Applicants note that the epoxy binding layer for wire can not be regarded to be a metal reinforcing sheet.

Further, the solder bump 7 in Kamoi, which the Examiner has regarded as a bump-like pad, is fixed on the semiconductor element 5. Claim 1 recites "the face for mounting a semiconductor element comprising pads through which the substrate is connected to the semiconductor element to be mounted thereon." Although the Kamoi reference does not explicitly state this, it is common practice for a bump to be formed on a semiconductor element. Kamoi describes adhering the wiring 3a to the package using epoxy, but Kamoi does not describe formation of bumps on the substrate in connection with the production process described with reference to Figure 2. The two are not equivalent. As recited in the instant specification, at page 7, lines 16-21, "as a result of using such bump-shaped pads, even a semiconductor element provided with electrode terminals having flat tips can be easily joined to the multilayered substrate of the present invention. In the device of Kamoi, it would not be possible to connect a semiconductor element having electrode terminals having flat tips to the multilayered substrate of Kamoi. Thus, Kamoi does not disclose pads of a package formed in a bump-like shape, as recited in claim 1. It is therefore believed the instant invention is not anticipated by nor obvious over Kamoi, and Applicants respectfully request reconsideration and allowance of the pending claims.

No fees are believed due for this response. Should any fees be deemed necessary, however, please charge the required amount to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310.

Respectfully submitted,

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